Dn Semiconductor  Title - Contact Phone - Contact*  Email - Contact*  Product-Env-Stewards Product-Env-Stewards Authorized Representative* Product-Env-Stewards	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name*  Company unique ID  Unique ID Authority  Response Date*  2021-02-04  2021-02-04  Contact Name  Title - Contact  Title - Contact  Product-Env-Stewards  Product-Env	752-21.1											ials and Mi	fg Informat	ion	
In Semiconductor    Phone - Contact Name   Title - Contact	upplier Informa	ntion								,			<u> </u>		
Title - Contact Name Product Env-Stewards Product	Company name* Comp				Company unique ID			Unique ID Authority				Response Date*			
Product Env-Stewards Authorized Representative* Title - Representative Product Enviro Compliance Product Enviro Compliance Product Enviro Compliance NA Product Env-Stewards @onsemi.com Product Env-Stewards @onsemi.com NA	n Semiconductor											2021-02-04			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit To Wanufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy  Title - Representative  Phone - Representative* NA Product-Env-Stewards@onsemi.com  Manufacturing Site Weight* UOM Unit To Requester Item Number NA Product-Env-Stewards@onsemi.com  Version Manufacturing Site Weight* UOM Unit To Representative* Phone - Representative*  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds Sec	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Unit 7  SOT-23 2N4117 MARKED 61A  2021-02-04  CN1  8.706  mg  Each  Manufacturing Process Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Matte Tin (Sn) - annealed  CU Alloy  1  260  C  30  seconds  3  Comments	Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	tative*		Title - Representative			I	Phone - Representative*				Email - Representative*			
MMBF4117   SOT-23 2N4117 MARKED 61A   2021-02-04   CN1   8.706   mg   Each	Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Item Number	Mfr Item	n Number Mfr Item Name				Effective Date	e Version	ı İ	Manufacturing Site		Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  Comments			MMBF41	117	SOT-23 2N4117 M	ARKED 61A		2021-02-04		(	CN1	8	3.706	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments										_					
omments				·		L Rating							per of Reflow Cyc	eles	
		(Sn) - annealed	C	U Alloy	1			260		<u> C</u>	30	secon	ds 3		
vei 1 - maximum time at peak temperature during soldering is 10-30 seconds				1. 1. 1. 10.0	10										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	led					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the company that the company tha	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit ide in you believe may apply. If the part is an assembly is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not e at least as comprehensive as the hts and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the					
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.048	mg	Supplier	Silicon (Si)	7440-21-3		0.048	mg
Lead Frame	2.371	mg	Supplier	Silver (Ag)	7440-22-4		0.008	mg
			Supplier	Manganese (Mn)	7439-96-5		0.019	mg
			Supplier	Silicon (Si)	7440-21-3		0.007	mg
			В	Nickel (Ni)	7440-02-0		0.995	mg
			Supplier	Iron (Fe)	7439-89-6		1.342	mg
Mold Compound-Black	6.061	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.21	mg
			Supplier	Carbon Black (C)	1333-86-4		0.061	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.79	mg
Plating	0.206	mg	Supplier	Tin (Sn)	7440-31-5		0.206	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg